

**IN THE CLAIMS:**

1. (Previously Presented) A dicing/die bonding sheet adhesively bonded to a semiconductor wafer prior to the dicing of said semiconductor wafer, wherein said dicing/die bonding sheet is provided with a base film, an undercoat layer formed on said base film, and a silicone based adhesive agent layer formed on said undercoat layer and having an adhesive surface adhesively bonded to said semiconductor wafer.
2. (Previously Presented) The dicing/die bonding sheet according to claim 1, wherein said silicone based adhesive agent layer can be stripped from said undercoat layer after bonding to said semiconductor wafer.
3. (Previously Presented) The dicing/die bonding sheet according to claim 1, wherein said undercoat layer is a laminate made up of at least two layers.
4. (Previously Presented) The dicing/die bonding sheet according to claim 1, wherein said base film has a surface area that is not less than said semiconductor wafer.
5. (Previously Presented) The dicing/die bonding sheet according to claim 1, which is coated with a strippable protective layer.

6. (Withdrawn) A method of preparing the dicing/die bonding sheet according to claim 1, which includes the step of forming the undercoat layer and the silicone based adhesive agent layer on the base film.

7. (Withdrawn) The method of preparing a dicing/die bonding sheet according to claim 1, which includes the step of forming the silicone based adhesive agent layer and the undercoat layer on a stripping layer, the step of applying the base film to a surface of the undercoat layer, and the step of peeling off the stripping layer.

8. (Withdrawn) The method of preparing a dicing/die bonding sheet according to claim 7, which further includes the step of forming a strippable protective layer on the silicone based adhesive agent layer after the step of peeling off the stripping layer.

9. (Withdrawn) The method of preparing a dicing/die bonding sheet according to claim 5, which includes the step of forming the silicone based adhesive agent layer and the undercoat layer on the strippable protective layer and the step of applying the base film to a surface of the undercoat layer.

10. (Previously Presented) The dicing/die bonding sheet according to claim 2, wherein said undercoat layer is a laminate made up of at least two layers.

11. (Previously Presented) The dicing/die bonding sheet according to claim 2, wherein said base film has a surface area that is not less than said semiconductor wafer.

12. (Previously Presented) The dicing/die bonding sheet according to claim 3, wherein said base film has a surface area that is not less than said semiconductor wafer.

13. (Previously Presented) The dicing/die bonding sheet according to claim 10, wherein said base film has a surface area that is not less than said semiconductor wafer.

14. (Previously Presented) The dicing/die bonding sheet according to claim 2, which is coated with a strippable protective layer.

15. (Previously Presented) The dicing/die bonding sheet according to claim 3, which is coated with a strippable protective layer.

16. (Previously Presented) The dicing/die bonding sheet according to claim 4, which is coated with a strippable protective layer.

17. (Previously Presented) The dicing/die bonding sheet according to claim 10, which is coated with a strippable protective layer.

18. (Previously Presented) The dicing/die bonding sheet according to claim 11, which is coated with a strippable protective layer.

19. (Previously Presented) The dicing/die bonding sheet according to claim 12, which is coated with a strippable protective layer.

20. (Previously Presented) The dicing/die bonding sheet according to claim 13, which is coated with a strippable protective layer.